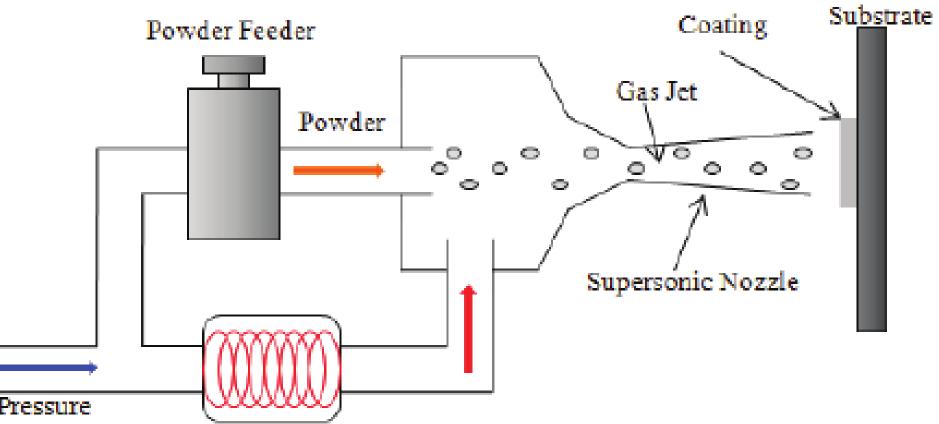
## MATERIAL CHARACTERIZATION OF COLD SPRAYED 3D PRINTED COPPER PARTS

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## Introduction

- "Cold Spray" is an additive manufacturing process traditionally used as a tool to repair metal structures/parts.
- Often used to repair aircraft structures that receive extensive wear and would otherwise require often and expensive replacement.
- Spee3D, an Australian research and development company, developed the worlds available additive commercially first manufacturing machine which uses cold spray to build 3D objects.



High Pressure Working Gas

Figure 1: Cold spray diagram

- Metal powder sprayed through rocket nozzle.
- Mechanical bond particles formed when plastically deform.



Gas Heater

Figure 2: Spee3D printer in action

## **Objectives**

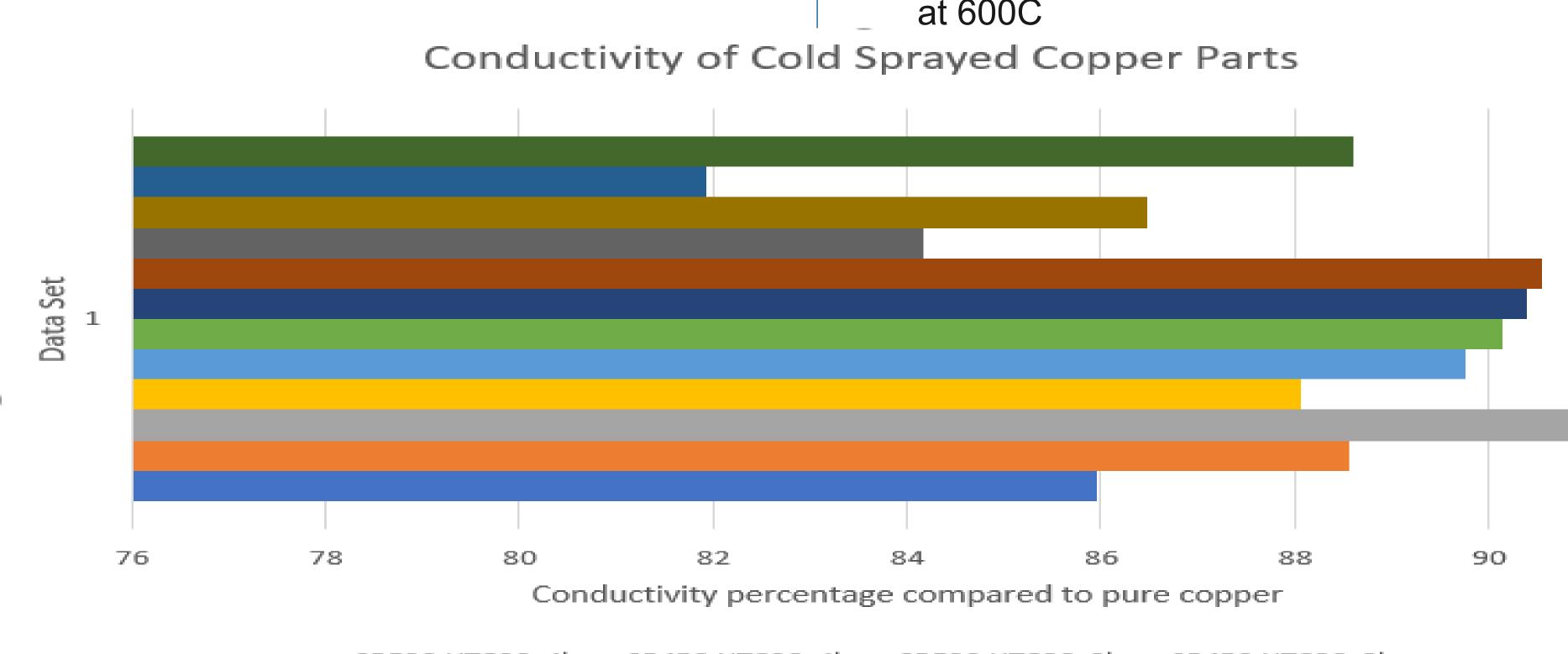
- sprayed parts for future Characterize cold applications.
- Explore printing parameters maximize to conductivity, ductility and strength.
- Experiment with different annealing times and temperatures to determine ideal post processing procedures.
- Compare specimen conductivity, strength, and ductility to that of "pure" copper.

Specimens printed via cold spray in the Spee3D are printed in environmental conditions. Although heat is not used to bond particles together, there is heat produced in the process. This heat leads to oxidation between layers. The cold spray process



## Procedure

- Rectangular test samples printed onto aluminum substrates.
- Specimens machined to achieve uniform crosssectional area.
- Using a Fischer Sigmascope, eddy current testing on samples from each category was performed to determine conductivity.
- Compared conductivity data to flexural test data previously done on similar specimens printed on the same machine.





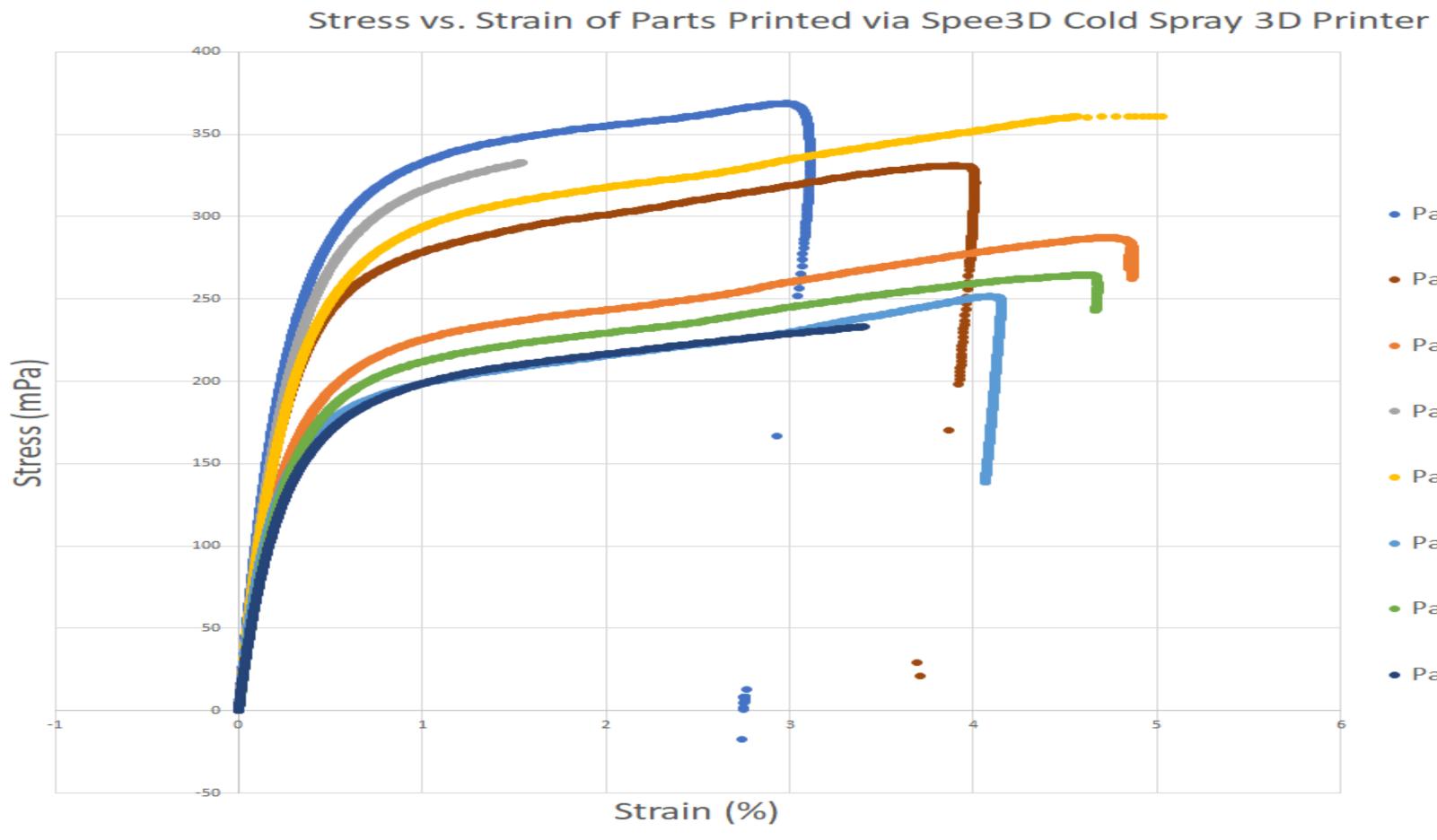


Figure 4: Comparison of specimens of varied printing and post-processing methods



## Results

- Higher sprayed-at temperatures are generally slightly higher in conductivity.
- Strong correlation between conductivity and ductility at all parameters.
- Annealing at 500C for 4 hours appears to be best post-processing treatment for obtaining max conductivity and ductility.
- Increased length spent annealing positively impacts both strength, ductility, and conductivity
- Dissipation of oxidation between layers observed in all specimens
- Imperfections become magnified when annealed at 600C

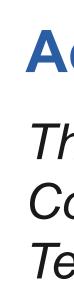
SP500 HT600x4hr SP450 HT600x4hr SP500 HT600x2hr SP450 HT600x2hr SP500 HT500x4hr SP450 HT500x4hr SP500 HT500x2hr SP450 HT500x2hr

### **Figure 3:** Conductivity percentages of printed parts \*\*Conductivity of pure copper is 100\*\*

<ul> <li>Part #1: SP425 HT400x2hr</li> </ul>
<ul> <li>Part #2: SP425 HT500x2hr</li> </ul>
<ul> <li>Part #3: SP425 HT650x2hr</li> </ul>
• Part #4: SP500 HT400x2hr
<ul> <li>Part #5: SP500 HT500x2hr</li> </ul>
<ul> <li>Part #6: SP500 HT650x2hr</li> </ul>
• Part #7: SP500 HT650x6hr
<ul> <li>Part #8: SP500 HT800x2hr</li> </ul>

## **Path Forward**

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 Replicate previous four-point flexural test results with current specimens:

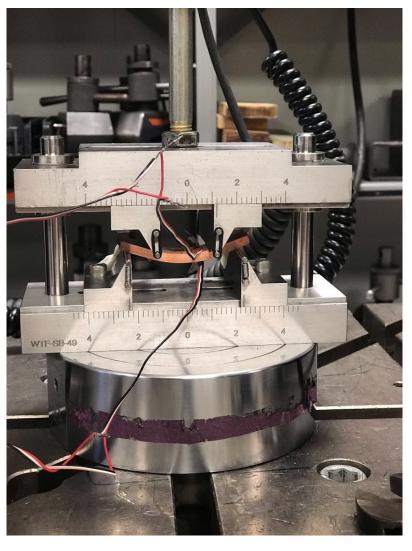
Apply strain gauges to each sample

Follow procedures outlined in ASTM D790

• All samples to be tested in Instron 5567 Universal Testing Machine with 5 kN load cell and strain rate of 0.5 inches per minute

• Flexural stress ( $\sigma_f$ ) calculated by

3 FL  $\frac{1}{4} \frac{1}{bd^2}$ , where  $\sigma_f =$ F is load *L* is length of support span *b* is the width of the specimen *d* is the thickness of the specimen



**Figure 5:** Four-point flexural testing in progress

## **Future Work**

• Apply data to future projects

Replicate results

coating Investigate and various substrates

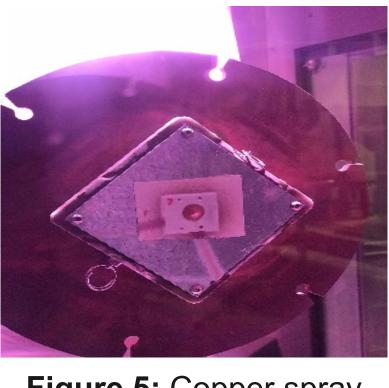


Figure 5: Copper spray adhering to zirconia ceramic

Co-Sponsored by:





Figure 7: Shaped charge liner

## Acknowledgements

This work is supported by the Center of Composite Materials and the Applications Technology Transfer Laboratory.

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